## WHAT IS CLAIMED IS:

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- 1. A high voltage transfer circuit, comprising:
- a first high voltage switch for transferring a high voltage generated within a chip to the outside of the chip according to a clock signal and a first control signal; and
  - a second high voltage switch for transferring the high voltage generated outside the chip to the inside of the chip according to the clock signal and a second control signal.
- 2. The high voltage transfer circuit as claimed in claim 1, wherein the first high voltage switch comprises:
  - a first switch for transferring the first control signal to a first node;
  - a second switch for transferring the high voltage generated within the chip to a second node according to the potential of the first node;
- a capacitor for controlling the potential of the second node according to the clock signal;
  - a third switch for transferring a voltage of the second node to the first node according to the potential of the second node; and
- a fourth switch for transferring the high voltage generated within the 20 chip to the outside of the chip according to the potential of the first node.
  - 3. The high voltage transfer circuit as claimed in claim 1, wherein the second high voltage switch comprises:
    - a first switch for transferring the second control signal to a first node;

a second switch for transferring the high voltage generated outside the chip to a second node according to the potential of the first node;

a capacitor for controlling the potential of the second node according to the clock signal;

a third switch for transferring a voltage of the second node to the first node according to the potential of the second node; and

a fourth switch for transferring the high voltage generated outside the chip to the inside of the chip according to the potential of the first node.

4. A high voltage transfer circuit, comprising:

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a pumping circuit for generating a high voltage necessary for an operation of a flash memory cell, and supplying the high voltage to an internal circuit;

a high voltage pad for receiving the high voltage generated from the pumping circuit, or the high voltage generated from the outside;

a first high voltage switch for transferring the high voltage generated from the pumping circuit to the high voltage pad according to a clock signal and a first control signal in a monitoring mode; and

a second high voltage switch for transferring the high voltage supplied to the high voltage pad from the outside to an internal circuit according to the clock signal and a second control signal in an external voltage supply mode.

5. The high voltage transfer circuit as claimed in claim 4, wherein the first high voltage switch comprises:

- a first NMOS transistor driven by a power supply voltage, for transferring the first control signal to a first node;
- a second NMOS transistor for transferring the high voltage generated within the chip to a second node according to the potential of the first node;
- a capacitor for controlling the potential of the second node according to the clock signal;
  - a third NMOS transistor for transferring a voltage of the second node to the first node according to the potential of the second node; and
- a fourth NMOS transistor for transferring the high voltage generated

  within the chip to the outside of the chip according to the potential of the first node.
  - 6. The high voltage transfer circuit as claimed in claim 4, wherein the second high voltage switch comprises:
  - a first switch driven by a power supply voltage, for transferring the second control signal to a first node;

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- a second NMOS transistor for transferring the high voltage generated outside the chip to a second node according to the potential of the first node;
- a capacitor for controlling the potential of the second node according to the clock signal;
  - a third NMOS transistor for transferring a voltage of the second node to the first node according to the potential of the second node; and

a fourth NMOS transistor for transferring the high voltage generated outside the chip to the inside of the chip according to the potential of the first node.